

Technical data sheet



Product: 5622

Manufacturer: DOWSIL

Product group: KLEBSTOFF

Article group: 1-K SILIKON

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DOWSIL™ TC-5622 THERMALLY CONDUCTIVE COM

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DOWSIL™ TC-5622 Thermally Conductive Compound

Gray, flowable, non-curing thermally conductive compound

Features & Benefits

- Solventless formulation
- Easy application
- Low thermal resistance
- High thermal conductivity
- Good stability and reliability

Composition

- Filled polydimethylsiloxane

Applications

- DOWSIL™ TC-5622 Thermally Conductive Compound is designed to provide efficient thermal transfer for the cooling of modules, including computer MPUs and power modules.

Typical Properties

Specification Writers: These values are not intended for use in preparing specifications.

| Property | Unit | Result |
|--|-----------------------|--------|
| Viscosity | cP | 95,000 |
| | Pa-sec | 95 |
| Specific Gravity (Uncured) | | 2.5 |
| Thermal Conductivity | W/mK | 4.3 |
| Thermal Resistance at 25 N/cm ² | °C*cm ² /W | 0.06 |
| Bond Line Thickness | Inch | 0.0008 |
| | mm | 0.02 |

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DOWSIL™ TC-5622 Thermally Conductive Compound

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|---|---|
| Description | <p>Dow thermally conductive compounds are grease like silicone materials, heavily filled with heat-conductive metal oxides. This combination promotes high thermal conductivity, low bleed and high-temperature stability. The compounds are designed to maintain a positive heat sink seal to improve heat transfer from the electrical device or the PCB system assembly to the heat sink or chassis, thereby increasing the overall efficiency of the device. PCB system assemblies are continually designed to deliver higher performance. Especially in the area of consumer devices, there is also a continual trend towards smaller, more compact designs. In combination these factors typically mean that more heat is generated in the device. Thermal management of PCB system assemblies is a primary concern of design engineers. A cooler device allows for more efficient operation and better reliability over the life of the device. As such, thermally conductive compounds play an integral role here. Thermally conductive materials act as a thermal “bridge” to remove heat from a heat source (device) to the ambient via a heat transfer media (i.e. heat sink). These materials have properties such as low thermal resistance, high thermal conductivity, and can achieve thin Bond Line Thicknesses (BLTs) which can help to improve the transfer of heat away from the device. Thermal greases have advantage over other TIMs due to their relatively low cost, ease of application on to heat sinks (screen printing), and ease of re-work.</p> |
| Application Methods | <ul style="list-style-type: none"> • Screen print • Stencil print • Dispense |
| Solvent Exposure | <p>In general, the product is resistant to minimal or intermittent solvent exposure, however best practice is to avoid solvent exposure altogether.</p> |
| Usable Life And Storage | <p>The product should be stored in its original packaging with the cover tightly attached to avoid any contamination. Store in accordance with any special instructions listed on the product label. The product should be used by the indicated Exp. Date found on the label.</p> |
| Handling Precautions | <p>PRODUCT SAFETY INFORMATION REQUIRED FOR SAFE USE IS NOT INCLUDED IN THIS DOCUMENT. BEFORE HANDLING, READ PRODUCT AND SAFETY DATA SHEETS AND CONTAINER LABELS FOR SAFE USE, PHYSICAL AND HEALTH HAZARD INFORMATION. THE SAFETY DATA SHEET IS AVAILABLE ON THE DOW WEBSITE AT WWW.CONSUMER.DOW.COM, OR FROM YOUR DOW SALES APPLICATION ENGINEER, OR DISTRIBUTOR, OR BY CALLING DOW CUSTOMER SERVICE.</p> |
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